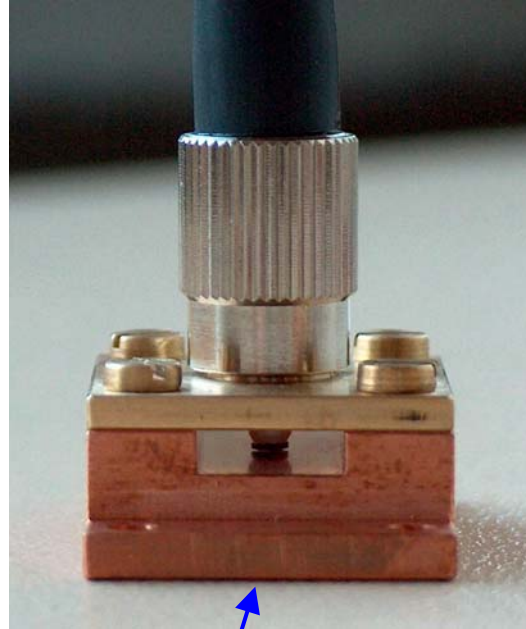


FC passive heat sink specification sheet

Fibre coupled SAM on passive heat sink



The copper baseplate has to be mounted on a heat sink with a good thermal conductivity.

The SAM chip is fixed on the fiber end. Thermal contact between the SAM and the copper baseplate is made with a small amount of a thermal conducting paste. The copper baseplate has to be mounted on a heat sink with good thermal conductivity.

assembly instructions

(note: during shipment the connector of the fiber patch cable is not plugged into the passive heat sink)

1. A small portion of a heat conducting paste should be applied to the lower side of the SAM chip (e.g. by the use of a utility, like a needle or a similar tool) mounted on the end face of the FC/PC connector. Do not use too much of the conducting paste! For example see figure 2. This procedure ensures a good thermal conductivity of the SAM chip to the copper heat sink.



figure 1: SAM chip on FC/PC connector end face



figure 2: same connector as figure 1 with heat conducting paste

2. Carefully insert the FC/PC plug with the chip in the female connector at the top plate. Smoothly tighten the coupling ring until the chip touches the copper surface of the baseplate. Do not overtighten the connector, this may damage the chip!

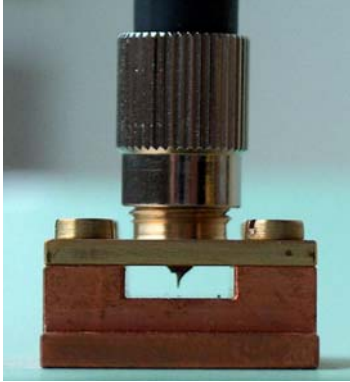


figure 3: FC/PC connector inserted in the passive heat sink

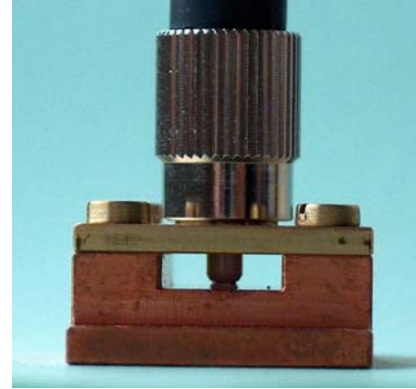


figure 4: the SAM chip is in contact with the baseplate, stop tighten the coupling ring